

CSD18536KTT 60 V N-Channel NexFET™ Power MOSFET

1 Features

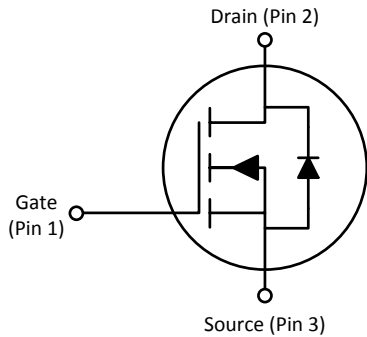
- Ultralow Q_g and Q_{gd}
- Low Thermal Resistance
- Avalanche Rated
- Pb-Free Terminal Plating
- RoHS Compliant
- Halogen Free
- D²PAK Plastic Package

2 Applications

- Secondary Side Synchronous Rectifier
- Motor Control

3 Description

This 60-V, 1.3-m Ω , D²PAK (TO-263) NexFET™ power MOSFET is designed to minimize losses in power conversion applications.



Product Summary

$T_A = 25^\circ\text{C}$		TYPICAL VALUE		UNIT
V_{DS}	Drain-to-Source Voltage	60		V
Q_g	Gate Charge Total (10 V)	108		nC
Q_{gd}	Gate Charge Gate-to-Drain	14		nC
$R_{DS(on)}$	Drain-to-Source On-Resistance	$V_{GS} = 4.5\text{ V}$	1.7	m Ω
		$V_{GS} = 10\text{ V}$	1.3	m Ω
$V_{GS(th)}$	Threshold Voltage	1.8		V

Ordering Information⁽¹⁾

DEVICE	QTY	MEDIA	PACKAGE	SHIP
CSD18536KTT	500	13-Inch Reel	D ² PAK Plastic Package	Tape & Reel
CSD18536KTTT	50			

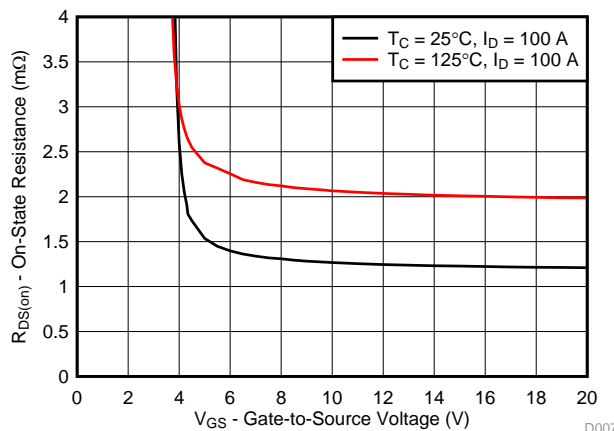
(1) For all available packages, see the orderable addendum at the end of the data sheet.

Absolute Maximum Ratings

$T_A = 25^\circ\text{C}$		VALUE	UNIT
V_{DS}	Drain-to-Source Voltage	60	V
V_{GS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current (Package limited)	200	A
	Continuous Drain Current (Silicon limited), $T_C = 25^\circ\text{C}$	349	A
	Continuous Drain Current (Silicon limited), $T_C = 100^\circ\text{C}$	247	A
I_{DM}	Pulsed Drain Current ⁽¹⁾	400	A
P_D	Power Dissipation	375	W
T_J, T_{stg}	Operating Junction and Storage Temperature	-55 to 175	$^\circ\text{C}$
E_{AS}	Avalanche Energy, Single Pulse $I_D = 128\text{ A}, L = 0.1\text{ mH}, R_G = 25\ \Omega$	819	mJ

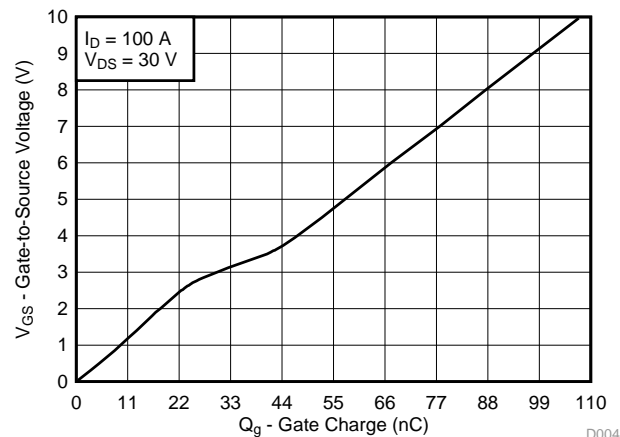
(1) Max $R_{\theta JC} = 0.4^\circ\text{C/W}$, pulse duration $\leq 100\ \mu\text{s}$, duty cycle $\leq 1\%$

$R_{DS(on)}$ vs V_{GS}



D007

Gate Charge



D004



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4 Revision History

DATE	REVISION	NOTES
March 2016	*	Initial release.

5 Specifications

5.1 Electrical Characteristics

(T_A = 25°C unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
STATIC CHARACTERISTICS						
B _V DSS	Drain-to-source voltage	V _{GS} = 0 V, I _D = 250 μA	60			V
I _{DSS}	Drain-to-source leakage current	V _{GS} = 0 V, V _{DS} = 48 V			1	μA
I _{GSS}	Gate-to-source leakage current	V _{DS} = 0 V, V _{GS} = 20 V			100	nA
V _{GS(th)}	Gate-to-source threshold voltage	V _{DS} = V _{GS} , I _D = 250 μA	1.4	1.8	2.2	V
R _{DS(on)}	Drain-to-source on-resistance	V _{GS} = 4.5 V, I _D = 100 A		1.7	2.2	mΩ
		V _{GS} = 10 V, I _D = 100 A		1.3	1.6	mΩ
g _{fs}	Transconductance	V _{DS} = 6 V, I _D = 100 A		312		S
DYNAMIC CHARACTERISTICS						
C _{iss}	Input capacitance	V _{GS} = 0 V, V _{DS} = 30 V, f = 1 MHz		8790	11430	pF
C _{oss}	Output capacitance			1410	1840	pF
C _{rss}	Reverse transfer capacitance			39	51	pF
R _G	Series gate resistance			0.7	1.4	Ω
Q _g	Gate charge total (10 V)	V _{DS} = 30 V, I _D = 100 A		108	140	nC
Q _{gd}	Gate charge gate-to-drain			14		nC
Q _{gs}	Gate charge gate-to-source			18		nC
Q _{g(th)}	Gate charge at V _{th}			17		nC
Q _{oss}	Output charge	V _{DS} = 30 V, V _{GS} = 0 V		230		nC
t _{d(on)}	Turn on delay time	V _{DS} = 30 V, V _{GS} = 10 V, I _{DS} = 100 A, R _G = 0 Ω		11		ns
t _r	Rise time			5		ns
t _{d(off)}	Turn off delay time			24		ns
t _f	Fall time			4		ns
DIODE CHARACTERISTICS						
V _{SD}	Diode forward voltage	I _{SD} = 100 A, V _{GS} = 0 V		0.9	1.0	V
Q _{rr}	Reverse recovery charge	V _{DS} = 30 V, I _F = 100 A, di/dt = 300 A/μs		323		nC
t _{rr}	Reverse recovery time			86		ns

5.2 Thermal Information

(T_A = 25°C unless otherwise stated)

THERMAL METRIC		MIN	TYP	MAX	UNIT
R _{θJC}	Junction-to-case thermal resistance			0.4	°C/W
R _{θJA}	Junction-to-ambient thermal resistance			62	°C/W

5.3 Typical MOSFET Characteristics

($T_A = 25^\circ\text{C}$ unless otherwise stated)

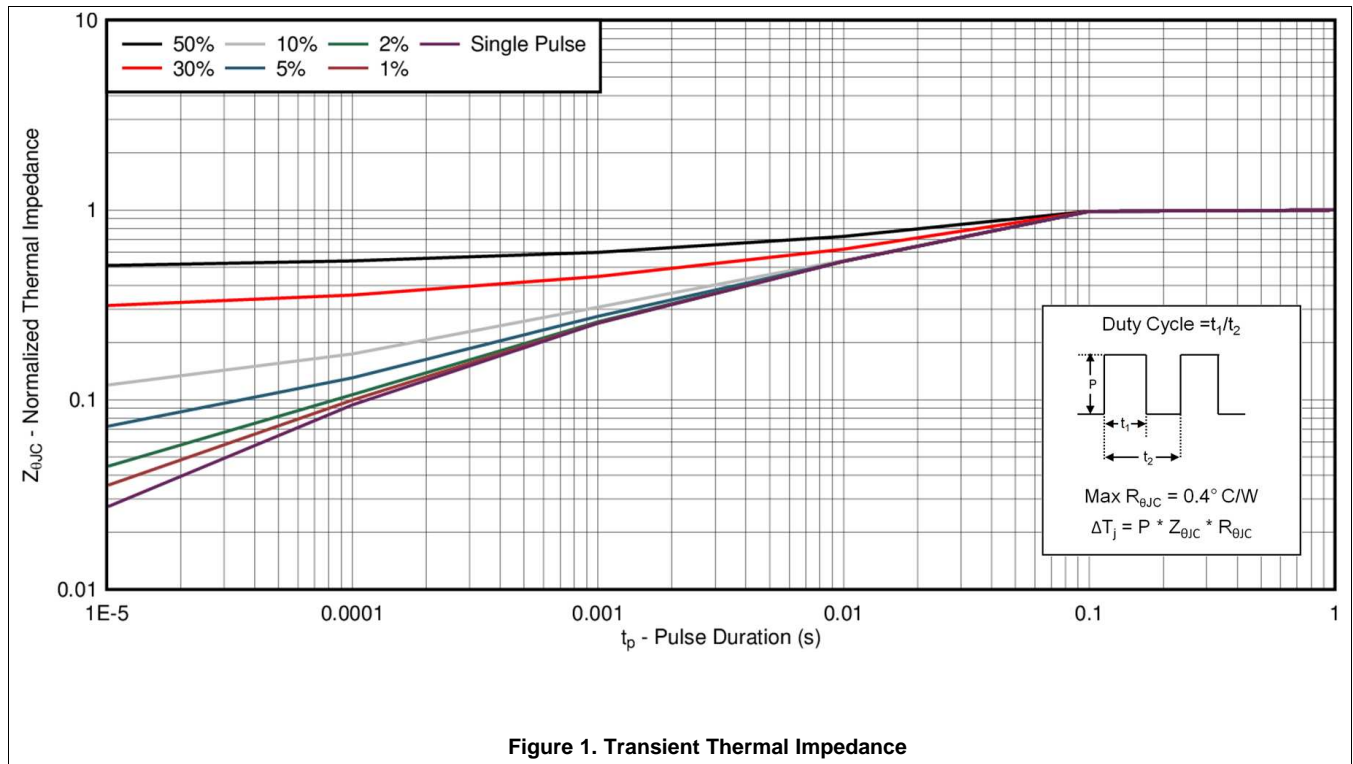


Figure 1. Transient Thermal Impedance

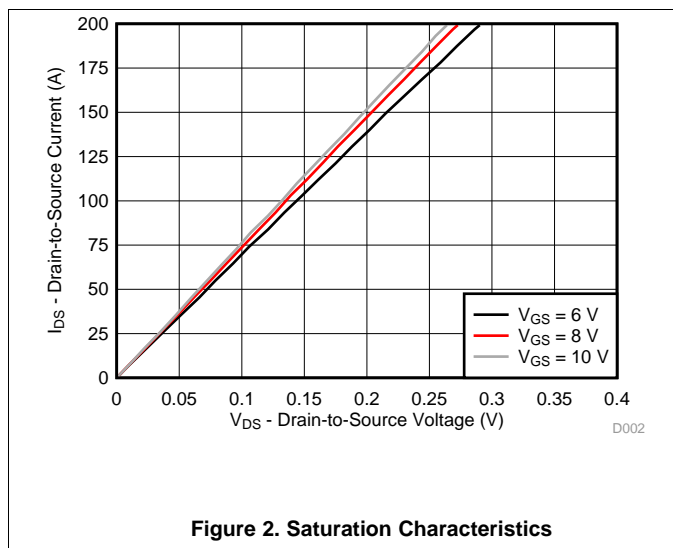


Figure 2. Saturation Characteristics

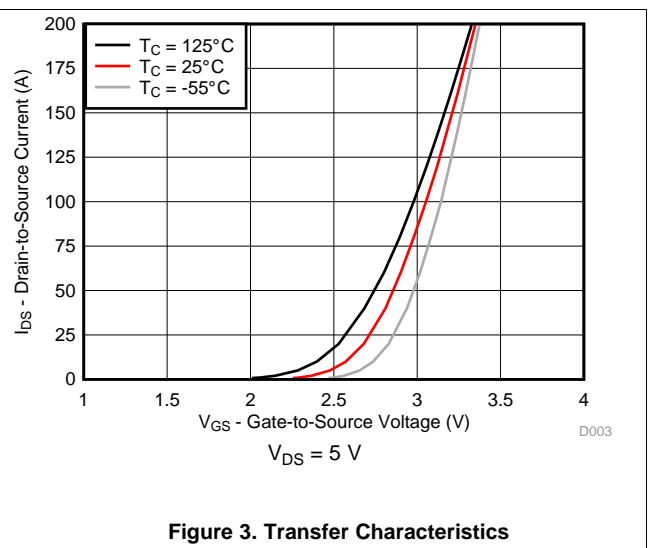


Figure 3. Transfer Characteristics

Typical MOSFET Characteristics (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)

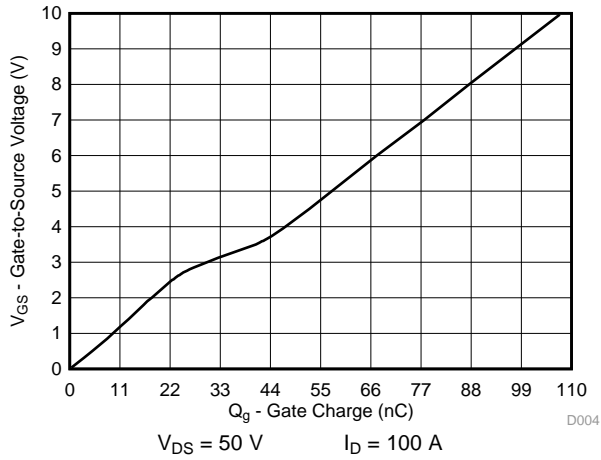


Figure 4. Gate Charge

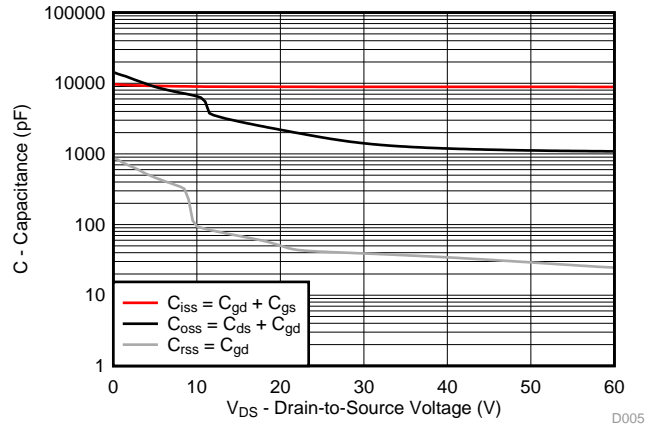


Figure 5. Capacitance

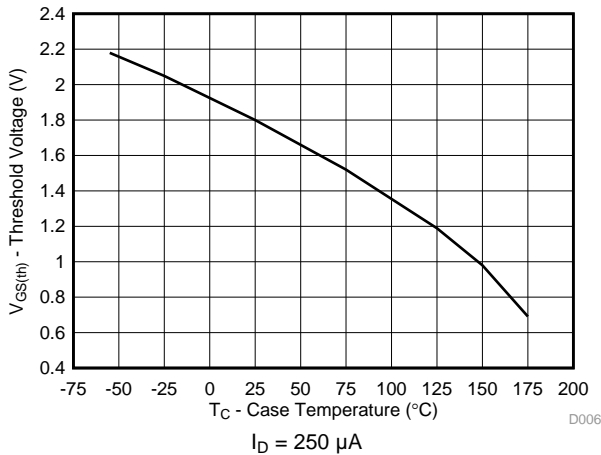


Figure 6. Threshold Voltage vs Temperature

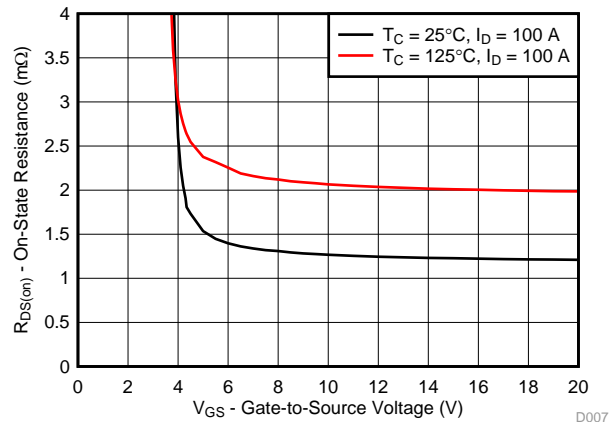


Figure 7. On-State Resistance vs Gate-to-Source Voltage

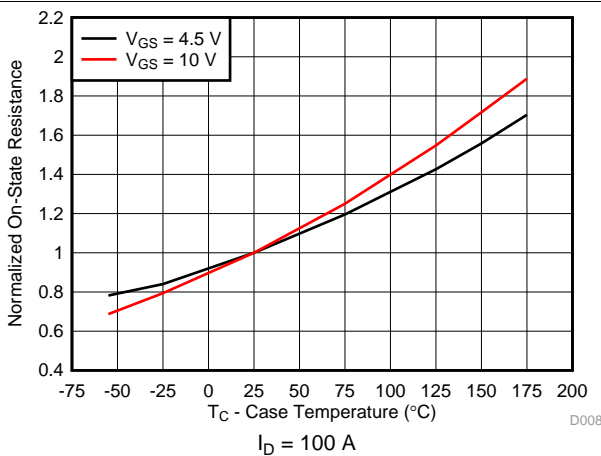


Figure 8. Normalized On-State Resistance vs Temperature

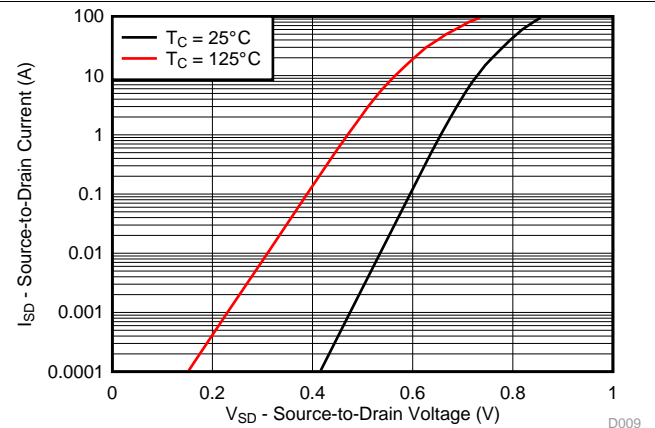


Figure 9. Typical Diode Forward Voltage

Typical MOSFET Characteristics (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)

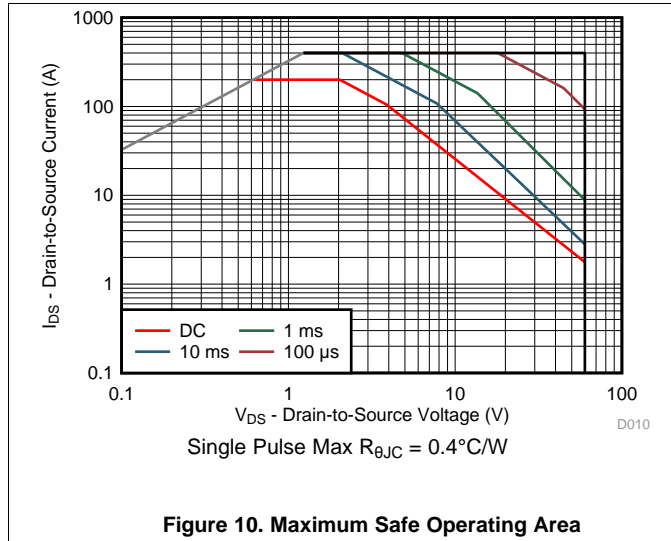


Figure 10. Maximum Safe Operating Area

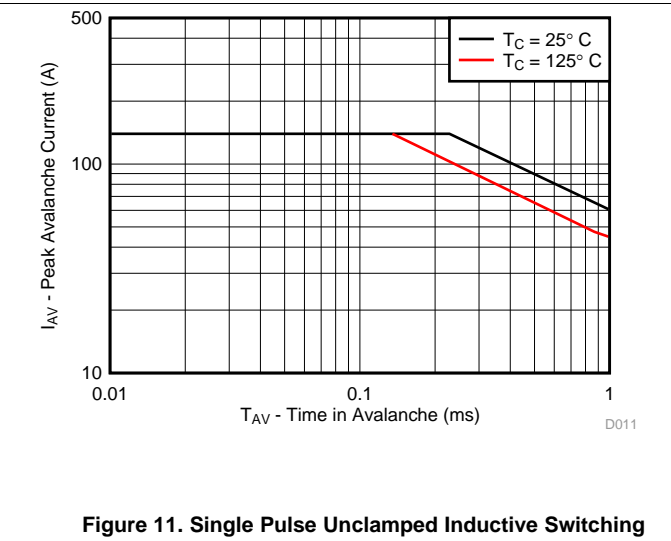


Figure 11. Single Pulse Unclamped Inductive Switching

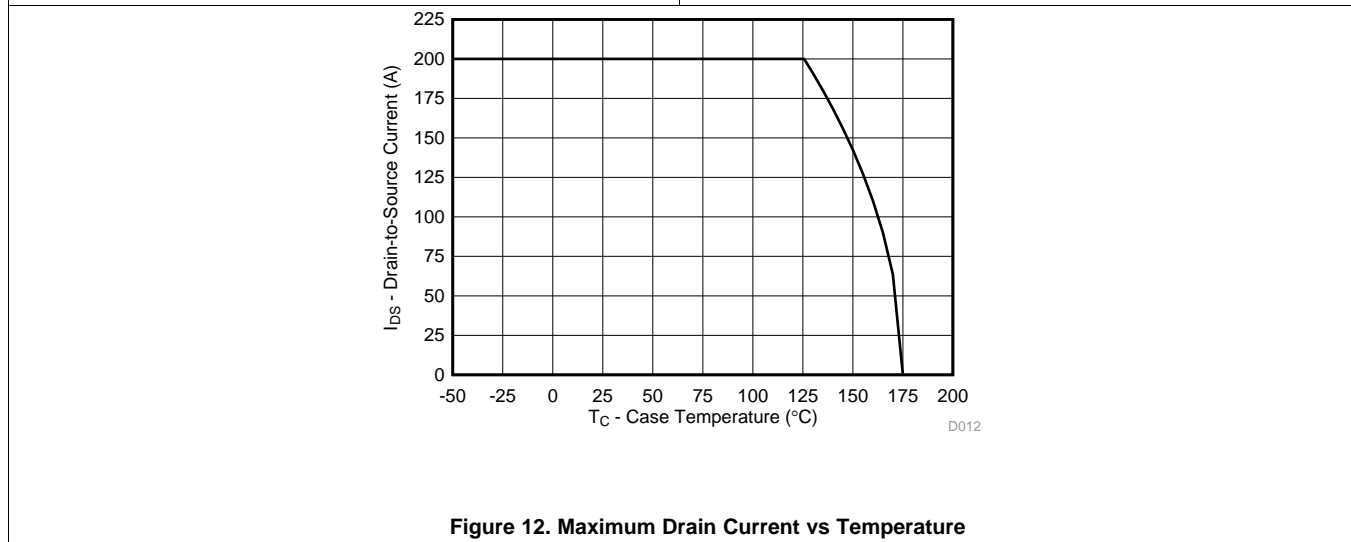


Figure 12. Maximum Drain Current vs Temperature

6 Device and Documentation Support

6.1 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

6.2 Trademarks

NexFET, E2E are trademarks of Texas Instruments.
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6.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

6.4 Glossary

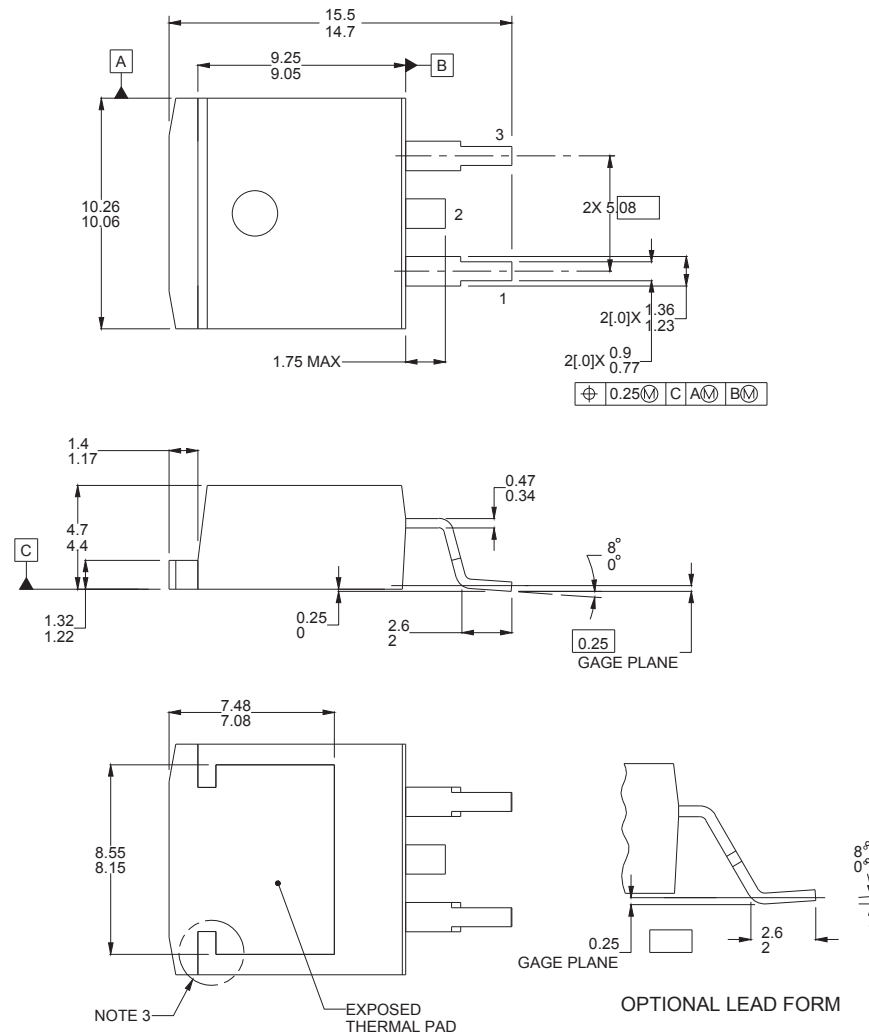
[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

7 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

7.1 KTT Package Dimensions



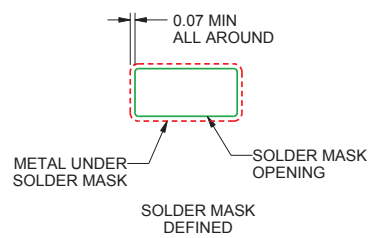
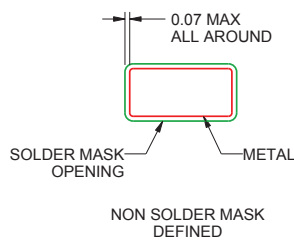
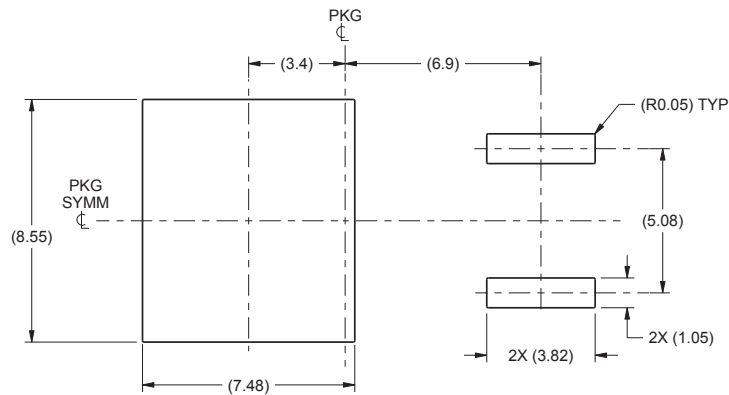
Notes:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Features may not exist and shape may vary per different assembly sites.

Pin Configuration

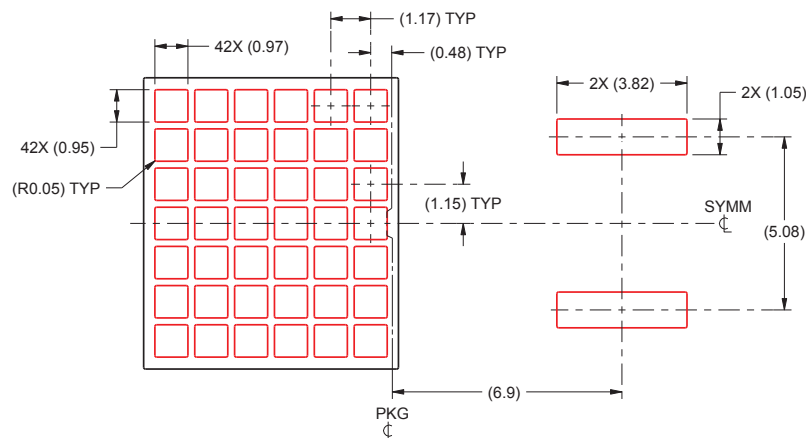
POSITION	DESIGNATION
Pin 1	Gate
Pin 2 / Tab	Drain
Pin 3	Source

7.2 Recommended PCB Pattern



For recommended circuit layout for PCB designs, see application note [SLPA005 – Reducing Ringing Through PCB Layout Techniques](#).

7.3 Recommended Stencil Opening (0.125 mm Stencil Thickness)



Notes:

1. This package is designed to be soldered to a thermal pad on the board. See application notes, *PowerPAD Thermally Enhanced Package* ([SLMA002](#)) and *PowerPAD Made Easy* ([SLMA004](#)) for more information.
2. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
3. Board assembly site may have different recommendations for stencil design.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CSD18536KTT	ACTIVE	DDPAK/ TO-263	KTT	3	500	Pb-Free (RoHS Exempt)	CU SN	Level-2-260C-1 YEAR	-55 to 175	CSD18536KTT	Samples
CSD18536KTTT	ACTIVE	DDPAK/ TO-263	KTT	3	50	TBD	Call TI	Call TI	-55 to 175		Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

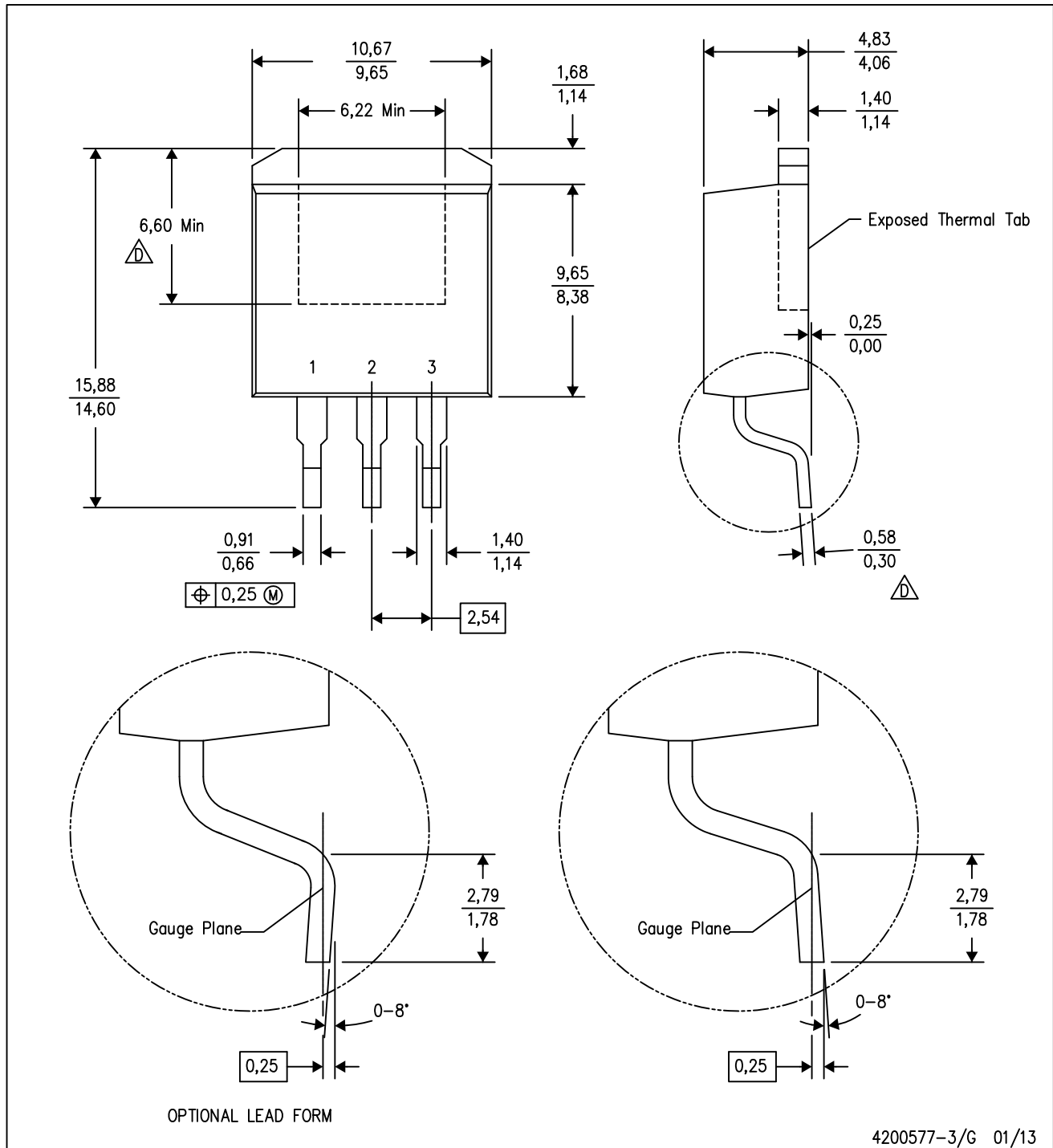
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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KTT (R-PSFM-G3)

PLASTIC FLANGE-MOUNT PACKAGE



4200577-3/G 01/13

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion. Mold flash or protrusion not to exceed 0.005 (0,13) per side.
- Falls within JEDEC TO-263 variation AA, except minimum lead thickness and minimum exposed pad length.

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